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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10082472	FILING DATE 02/22/2002	CLASS 438	SUBCLASS 101	GAU 202	EXAMINER ZARNEKE
**APPLICANTS: Yoshida Akito; 2827					
**CONTINUING DATA VERIFIED:					
** FOREIGN APPLICATIONS VERIFIED:					
PG-PUB		DO NOT PUBLISH <input checked="" type="checkbox"/>		RESCIND <input type="checkbox"/>	
Foreign priority claimed		<input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO	
35 USC 119 conditions met		<input type="checkbox"/> yes <input type="checkbox"/> no		W2K 1077	
Verified and Acknowledged Examiners's initials					
TITLE : Stacking structure for semiconductor devices using a folded over flexible substrate and method therefor					
U.S. DEPT. OF COMM./PAT. & TM.-PTO-438L (Rev. 12-94)					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Assistant Examiner	
ISSUE FEE		Total Claims	
Amount Due	Date Paid	Print Claim for O.G.	
		DRAWING	
		Sheets Drwg.	Figs. Drwg.
		Print Fig.	
		Application Examiner	
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	
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